

DECLARATION FOR PATENT APPLICATION

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am an original, first and sole inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled **HEATING FURNACE AND SEMICONDUCTOR WAFER HOLDING JIG ASSEMBLY AND PROCESS OF MANUFACTURING SEMICONDUCTOR DEVICES**, the specification of which:

☒ [X] is attached hereto.

☐ [] was filed on _____ as Application Serial No. _____.

☐ [] was filed on _____ under U.S. Express Mail No. _____.

☐ [] is set forth in PCT International Application No. _____;
filed on _____ and as amended Under PCT Article 19 on _____ (if any).

I/we hereby state that I/we have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I/we acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56.

I/we hereby claim the benefit under Title 35, United States Code, §119 of any United States provisional patent application, foreign application(s) for patent or inventor's certificate listed below and have also identified below any United States provisional patent application, foreign application for patent or inventor's certificate having a filing date before that of the above-identified application on which priority is claimed:

PRIOR FOREIGN APPLICATIONS: (ENTER BELOW IF APPLICABLE)			PRIORITY CLAIMED (MARK APPROPRIATE BOX BELOW)	
APP. NUMBER	COUNTRY	DAY/MONTH/YEAR FILED	YES	NO
2001-225713	Japan	26/July/2001	X	

I/we hereby claim the benefit under Title 35, United States Code, §120 of any United States patent application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I/we acknowledge the duty to disclose material information as defined in Title 37 Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

APPLICATION SERIAL NO.	FILING DATE	STATUS (MARK APPROPRIATE COLUMN BELOW)		
		PATENTED	PENDING	ABANDONED

I/we hereby appoint the following attorneys/agents to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith: George M. Thomas, Reg. No. 22,260; James W. Kayden, Reg. No. 31,532; Scott A. Horstemeyer, Reg. No. 34,183; Stephen R. Risley, Reg. No. 35,659; Jeffrey R. Kuester, Reg. No. 34,367; Daniel J. Santos, Reg. No. 40,158; Michael J. Tempel, Reg. No. 41,344; Daniel R. McClure, Reg. No. 38,962; Robert E. Stachler II, Reg. No. 36,934; David I. Kelley, Reg. No. 17,420; Reg. No. 41,344; David R. Risley, Reg. No. 39,345; Dan R. Gresham, Reg. No. 41,805; J. Scott Culpepper, Reg. No. 41,692; M. Paul Qualey, Reg. No. 43,024; Robert P. Biddle, Reg. No. 35,826; Robert A. Blaha, Reg. No. 43,502; Jennifer M. Gruber, Reg. No. 42,601; Raymond W. Armentrout, Reg. No. 45,866; Cynthia J. Lee, Reg. No. 46,033; N. Andrew Crain, Reg. No. 45,442; Monica H. Winghart, Reg. No. 46,790; Sami O. Malas, Reg. No. 44,893; Eric M. Ringer, Reg. No. 47,028; Robert B. Dulaney III, Reg. No. 47,539; Adam E. Crall, Reg. No. 46,646; William F. Heinze, Reg. No. 36,161; Christopher B. Linder, Ph.D., Reg. No. 47,751; Peter A. Nieves, Reg. No. 48,173; David Rodack, Reg. 47,034; Edwina T. Washington, Reg. No. 43,187.

Please address all telephone calls, in the first instance, to Daniel R. McClure at telephone number: (770) 933-9500.

Address all correspondence to:

Daniel R. McClure
THOMAS, KAYDEN, HORSTEMEYER
& RISLEY, L.L.P.
100 Galleria Parkway, N.W., Suite 1750
Atlanta, Georgia 30339-5948

I hereby declare that all statements made herein of my own knowledge are true and that all statement made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statement and the like so made are punishable by fine or imprisonment, or both under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Inventor's Signature: Mikio Takagi Date: 19. July, 2002

Full Name of First or Sole TAKAGI Last name: TAKAGI
Residence: 2578-1, Noborito Tama-Ku, Kawasaki-City, Kanagawa, Japan
Citizenship: Japan
Post Office Address: Same